IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfc Information			
upplier Inform	ation								,					
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2024-05-04			
Contact Name		Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-Env-Stewar	rds	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
uthorized Represer	ntative*	Title - Representative			P	Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number		Mfr Item Number		Mfr Item Name			Effective Date	Version	sion Manufacturing Site		V	Weight*	UOM	Unit Type
	QT7860 R		RFIC 5-7 GHz			2024-05-04		Т	TWU		98.552	mg	Each	
Ianufacturing I	Proccess Information	on									·		·	·
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S				Max Time at Peak	Temperatu	ure Numb	er of Reflow Cyc	eles			
SnAgCu		C	U Alloy	3			260	(2	30	second	ds 3		
omments														
ΓΤΕΝΤΙΟΝ: MSL	3 Rated item requires l	Bake and D	ry Pack (after	r electrical test)										
or more informatio	on regarding material co	omposition j	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale appl											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	21.06	mg	Supplier	Silicon (Si)	7440-21-3		21.06	mg
Mold Compound-Black	71.922	mg	Supplier	Carbon Black (C)	1333-86-4		0.3596	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		63.651	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		3.9557	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.9557	mg
Solder Ball	23.57	mg	Supplier	Silver (Ag)	7440-22-4		0.7071	mg
			Supplier	Tin (Sn)	7440-31-5		22.745	mg
			Supplier	Copper (Cu)	7440-50-8		0.1178	mg
Substrate	82.0	mg		Silica	proprietary data		0.0246	mg
			Supplier	Organic Resin	105391-33-1 / 1156-51-0 / 9003- 36-5		8.569	mg
			Supplier	Antifoamer and Leveling Agent	Proprietary Data		0.041	mg
			Supplier	Organic pigment	Proprietary Data		0.0082	mg
			Supplier	Phthalocyanine blue	147-14-8		0.0082	mg
			Supplier	Talc	14807-96-6		0.1148	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		14.022	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		8.569	mg
			В	Nickel (Ni)	7440-02-0		10.0122	mg
			Supplier	Gold (Au)	7440-57-5		2.173	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		3.9852	mg
			Supplier	Copper (Cu)	7440-50-8		33.374	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		1.0988	mg